

Notice of References Cited	Application/Control No. 10/804,737	Applicant(s)/Patent Under Reexamination ICHITSUBO ET AL.	
	Examiner Monica Lewis	Art Unit 2822	Page 1 of 1

U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-2005/0205986	09-2005	Ichitsubo et al.	257/690
	B	US-6,642,617	11-2003	Kawai, Takahisa	257/724
	C	US-6,462,950	10-2002	Pohjonen, Helena	361/704
	D	US-2004/0124522	07-2004	Lin, Shi-Tron	257/697
	E	US-6,727,761	04-2004	Apel, Thomas R.	330/295
	F	US-			
	G	US-			
	H	US-			
	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

FOREIGN PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
	O					
	P					
	Q					
	R					
	S					
	T					

NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Peter Van Zant, Microchip Fabrication, 2000, McGraw-Hill, Fourth Edition, Pages 391 and 507-509
	V	Charles A. Harper, Electronic Packaging and Interconnection Handbook, 2000, Third Edition, Page 7.20
	W	
	X	

*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.